- **D-C Triggered from Active-High or Active-Low Gated Logic Inputs**
- **Retriggerable for Very Long Output Pulses, Up to 100% Duty Cycle**
- **Overriding Clear Terminates Output Pulse**
- **'122 and 'LS122 Have Internal Timing Resistors**

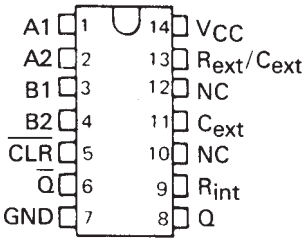
description

These d-c triggered multivibrators feature output pulse-duration control by three methods. The basic pulse time is programmed by selection of external resistance and capacitance values (see typical application data). The '122 and 'LS122 have internal timing resistors that allow the circuits to be used with only an external capacitor, if so desired. Once triggered, the basic pulse duration may be extended by retriggering the gated low-level-active (A) or high-level-active (B) inputs, or be reduced by use of the overriding clear. Figure 1 illustrates pulse control by retriggering and early clear.

The 'LS122 and 'LS123 are provided enough Schmitt hysteresis to ensure jitter-free triggering from the B input with transition rates as slow as 0.1 millivolt per nanosecond.

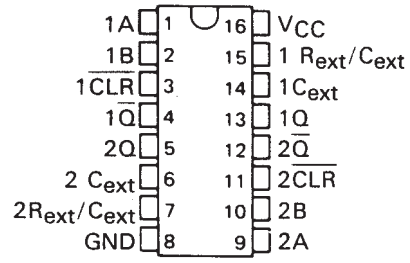
The R_{int} in nominall 10 kΩ for '122 and 'LS122.

SN54122, SN54LS122 . . . J OR W PACKAGE
SN74122 . . . N PACKAGE
SN74LS122 . . . D OR N PACKAGE
(TOP VIEW) (SEE NOTES 1 THRU 4)

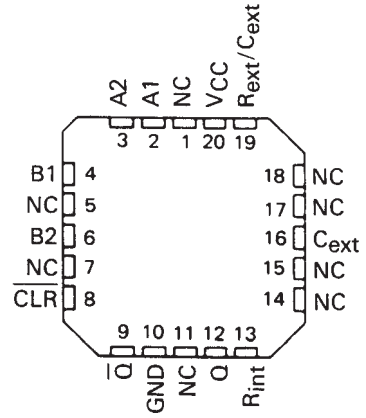


NOTES: 1. An external timing capacitor may be connected between C_{ext} and R_{ext}/C_{ext} (positive).
2. To use the internal timing resistor of '122 or 'LS122, connect R_{int} to V_{CC}.
3. For improved pulse duration accuracy and repeatability, connect an external resistor between R_{ext}/C_{ext} and V_{CC} with R_{int} open-circuited.
4. To obtain variable pulse durations, connect an external variable resistance between R_{int} or R_{ext}/C_{ext} and V_{CC}.

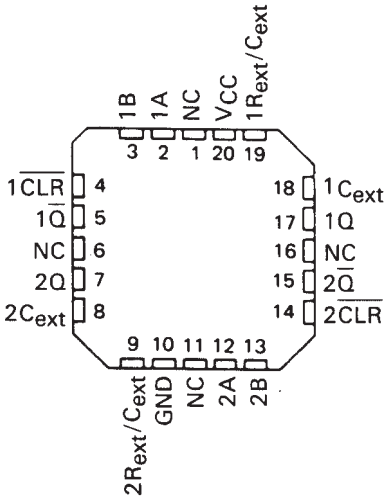
SN54123, SN54130, SN54LS123 . . . J OR W PACKAGE
SN74123, SN74130 . . . N PACKAGE
SN74LS123 . . . D OR N PACKAGE
(TOP VIEW) (SEE NOTES 1 THRU 4)



SN54LS122 . . . FK PACKAGE
(TOP VIEW) (SEE NOTES 1 THRU 4)



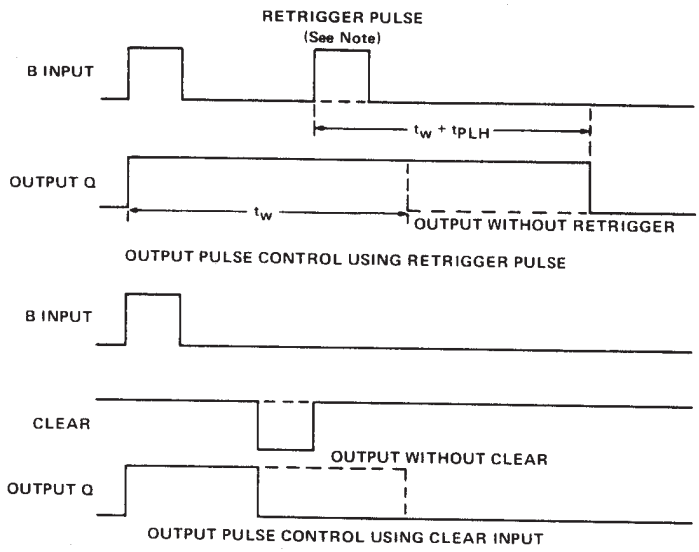
SN54LS123 . . . FK PACKAGE
(TOP VIEW) (SEE NOTES 1 THRU 4)



NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

description (continued)



NOTE: Retrigger pulses starting before 0.22 C_{ext} (in picofrads) nanoseconds after the initial trigger pulse will be ignored and the output duration will remain unchanged.

FIGURE 1–TYPICAL INPUT/OUTPUT PULSES

'122, 'LS122
FUNCTION TABLE

INPUTS					OUTPUTS	
CLEAR	A1	A2	B1	B2	Q	$\bar{Q}$
L	X	X	X	X	L	H
X	H	H	X	X	L†	H†
X	X	X	L	X	L†	H†
X	X	X	X	L	L†	H†
H	L	X	↑	H	⎍	⎎
H	L	X	H	↑	⎍	⎎
H	X	L	↑	H	⎍	⎎
H	X	L	H	↑	⎍	⎎
H	H	↓	H	H	⎍	⎎
H	↓	↓	H	H	⎍	⎎
H	↓	H	H	H	⎍	⎎
↑	L	X	H	H	⎍	⎎
↑	X	L	H	H	⎍	⎎

'123, '130, 'LS123
FUNCTION TABLE

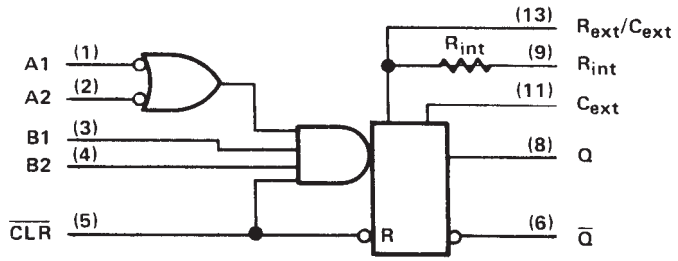
INPUTS			OUTPUTS	
CLEAR	A	B	Q	$\bar{Q}$
L	X	X	L	H
X	H	X	L†	H†
X	X	L	L†	H†
H	L	↑	⎍	⎎
H	↓	H	⎍	⎎
↑	L	H	⎍	⎎

See explanation of function tables on page

† These lines of the functional tables assume that the indicated steady-state conditons at the A and B inputs have been set up long enough to complete any pulse started before the set up.

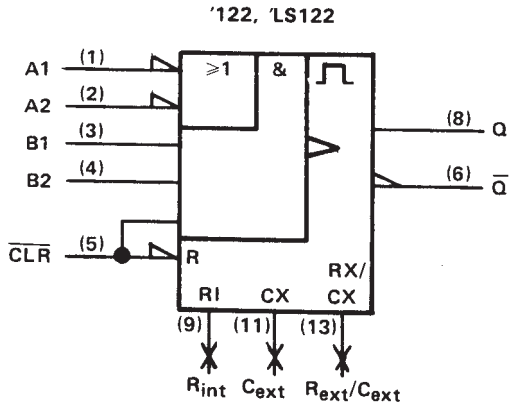
logic diagram (positive logic)

'122, 'LS122



logic symbol†

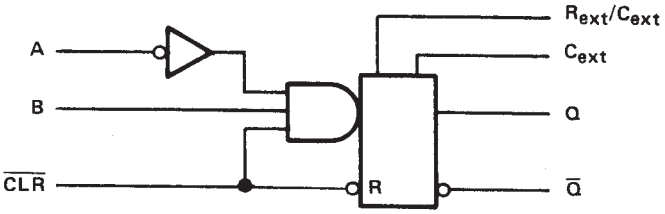
'122, 'LS122



R_{int} is nominally 10 kΩ for '122 and 'LS122

logic diagram (positive logic) (each multivibrator)

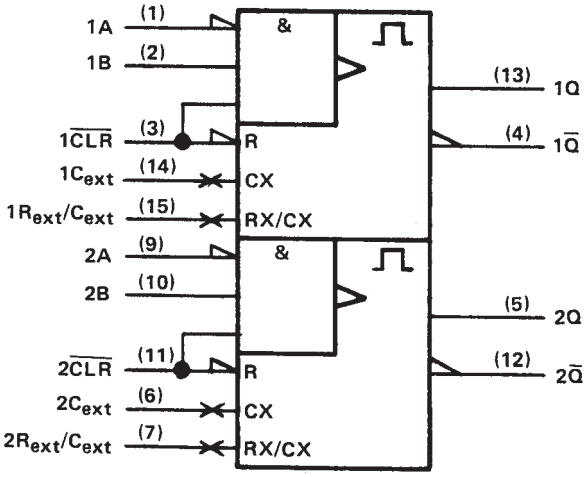
'123, '130, 'LS123



Pin numbers shown are for D, J, N, and W packages.

logic symbol†

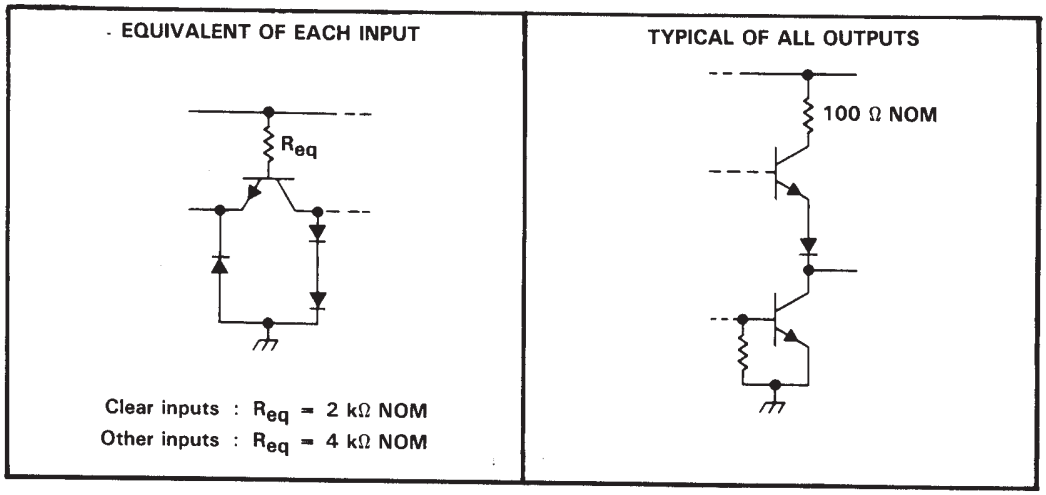
'123, '130, 'LS123



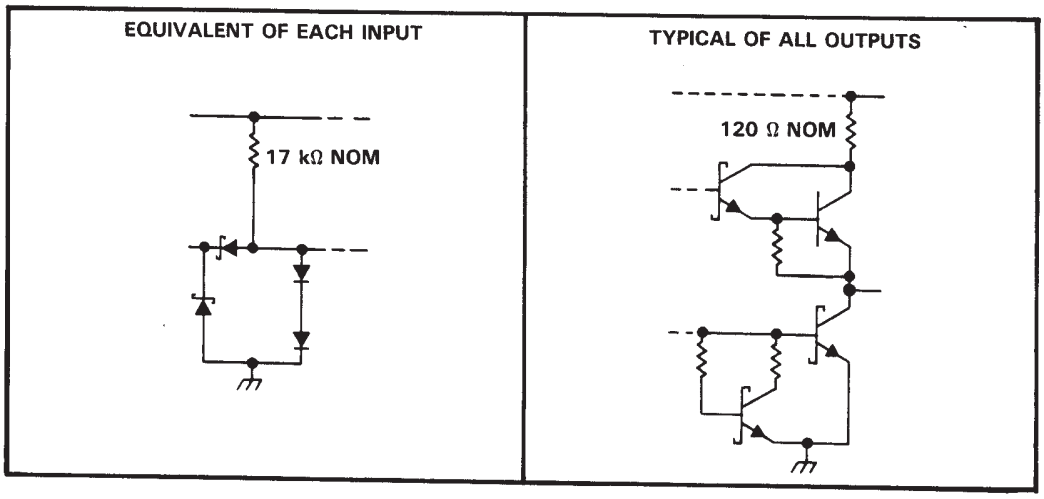
†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs

'122, '123, '130 CIRCUITS



'LS122, 'LS123 CIRCUITS



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage: '122, '123, '130 . . . . . 5.5 V
'LS122, 'LS123 . . . . . 7 V
Operating free-air temperature range: SN54' . . . . . −55°C to 125°C
SN74' . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54'			SN74'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−800			−800	μA
Low-level output current, I_{OL}			16			16	mA
Pulse duration, t_w	40			40			ns
External timing resistance, R_{ext}	5		25	5		50	kΩ
External capacitance, C_{ext}	No restriction			No restriction			
Wiring capacitance at R_{ext}/C_{ext} terminal			50			50	pF
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended free-air operating temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†	'122			'123, '130			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.8			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = −12 mA			−1.5			−1.5	V
V_{OH}	High-level output voltage		V_{CC} = MIN, I_{OH} = −800 μA, See Note 5	2.4	3.4		2.4	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, I_{OL} = 16 mA, See Note 5		0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	High-level input current	Data inputs	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
		Clear input				80			80	
I_{IL}	Low-level input current	Data inputs	V_{CC} = MAX, V_I = 0.4 V			−1.6			−1.6	mA
		Clear input				−3.2			−3.2	
I_{OS}	Short-circuit output current§		V_{CC} = MAX, See Note 5	−10		−40	−10		−40	mA
I_{CC}	Supply current (quiescent or triggered)		V_{CC} = MAX, See Notes 6 and 7		23	36		46	66	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.

NOTES: 5. Ground C_{ext} to measure V_{OH} at Q, V_{OL} at $\overline{Q}$, or I_{OS} at Q. C_{ext} is open to measure V_{OH} at $\overline{Q}$, V_{OL} at Q, or I_{OS} at $\overline{Q}$.
6. Quiescent I_{CC} is measured (after clearing) with 4.5 V applied to all clear and A inputs, B inputs grounded, all outputs open and R_{ext} = 25 kΩ. R_{int} of '122 is open.
7. I_{CC} is measured in the triggered state with 2.4 V applied to all clear and B inputs, A inputs grounded, all outputs open, C_{ext} = 0.02 μF, and R_{ext} = 25 kΩ. R_{int} of '122 is open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, see note 8

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'122, '130			'123			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	A	Q	C_{ext} = 0, C_L = 15 pF, R_{ext} = 5 kΩ, R_L = 400 Ω		22	33		22	33	ns
	B				19	28		19	28	
t_{PHL}	A	$\overline{Q}$			30	40		30	40	ns
	B				27	36		27	36	
t_{PHL}	Clear	Q			18	27		18	27	ns
t_{PLH}		$\overline{Q}$			30	40		30	40	
t_{wQ} (min)	A or B	Q			45	65		45	76	ns
t_{wQ}	A or B	Q	C_{ext} = 1000 pF, C_L = 15 pF, R_{ext} = 10 kΩ, R_L = 400 Ω	3.08	3.42	3.76	2.76	3.03	3.37	μs

¶ t_{PLH} = propagation delay time, low-to-high-level output
t_{PHL} = propagation delay time, high-to-low-level output
t_{wQ} = duration of pulse at output Q.

NOTE 8: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	SN54LS'			SN74LS'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−400			−400	μA
Low-level output current, I_{OL}			4			8	mA
Pulse duration, t_w	40			40			ns
External timing resistance, R_{ext}	5		180	5		260	kΩ
External capacitance, C_{ext}	No restriction			No restriction			
Wiring capacitance at R_{ext}/C_{ext} terminal			50			50	pF
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			SN54LS'			SN74LS'			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = V_{IL}max	V_{IH} = 2 V, I_{OH} = −400 μA		2.5	3.5		2.7	3.5		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = V_{IL}max	V_{IH} = 2 V,	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V				0.1			0.1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V				20			20	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V				−0.4			−0.4	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX			−20		−100	−20		−100	mA
I_{CC}	Supply current (quiescent or triggered)	V_{CC} = MAX,	See Note 13	'LS122		6	11		6	11	mA
				'LS123		12	20		12	20	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
NOTES: 12. To measure V_{OH} at Q, V_{OL} at Q, or I_{OS} at Q, ground R_{ext}/C_{ext}, apply 2 V to B and clear, and pulse A from 2 V to 0 V.
13. With all outputs open and 4.5 V applied to all data and clear inputs. I_{CC} is measured after a momentary ground, then 4.5 V, is applied to A or B inputs.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 8)

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A	Q	C_{ext} = 0, C_L = 15 pF,	R_{ext} = 5 kΩ, R_L = 2 kΩ		23	33	ns
	B					23	44	
t_{PHL}	A	$\overline{Q}$				32	45	ns
	B					34	56	
t_{PHL}	Clear	Q				20	27	ns
t_{PLH}		$\overline{Q}$				28	45	
t_{wQ} (min)	A or B	Q				116	200	ns
t_{wQ}	A or B	Q	C_{ext} = 1000 pF, C_L = 15 pF,	R_{ext} = 10 kΩ, R_L = 2 kΩ	4	4.5	5	μs

¶t_{PLH} = propagation delay time, low-to-high-level output
t_{PHL} = propagation delay time, high-to-low-level output
t_{wQ} = duration of pulse at output Q.
NOTE 8: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA FOR '122, '123, '130

For pulse durations when $C_{ext} \leq 1000$ pF, see Figure 4.

The output pulse duration is primarily a function of the external capacitor and resistor. For $C_{ext} > 1000$ pF, the output pulse duration (t_w) is defined as:

$$t_w = K \cdot R_T \cdot C_{ext}\left(1 + \frac{0.7}{R_T}\right)$$

where

K is 0.32 for '122, 0.28 for '123 and '130

R_T is in kΩ (internal or external timing resistance.)

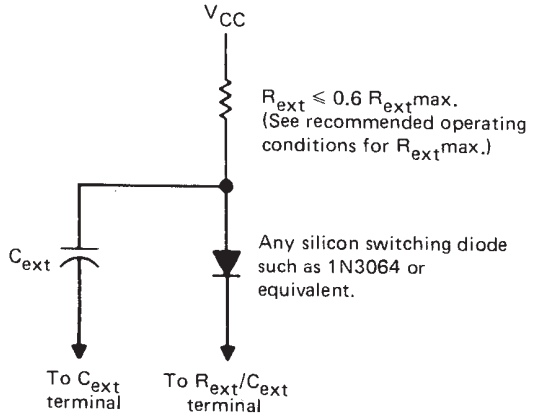
C_{ext} is in pF

t_w is in ns

To prevent reverse voltage across C_{ext}, it is recommended that the method shown in Figure 2 be employed when using electrolytic capacitors and in applications utilizing the clear function. In all applications using the diode, the pulse duration is:

$$t_w = K_D \cdot R_T \cdot C_{ext}\left(1 + \frac{0.7}{R_T}\right)$$

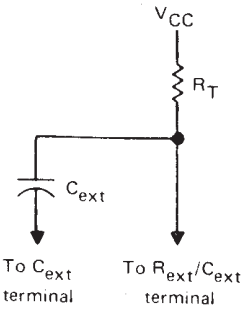
K_D is 0.28 for '122, 0.25 for '123 and '130



TIMING COMPONENT CONNECTIONS WHEN $C_{ext} > 1000$ pF AND CLEAR IS USED

FIGURE 2

Applications requiring more precise pulse durations (up to 28 seconds) and not requiring the clear feature can best be satisfied with the '121.



TIMING COMPONENT CONNECTIONS

FIGURE 3

TYPICAL OUTPUT PULSE DURATION
vs
EXTERNAL TIMING CAPACITANCE

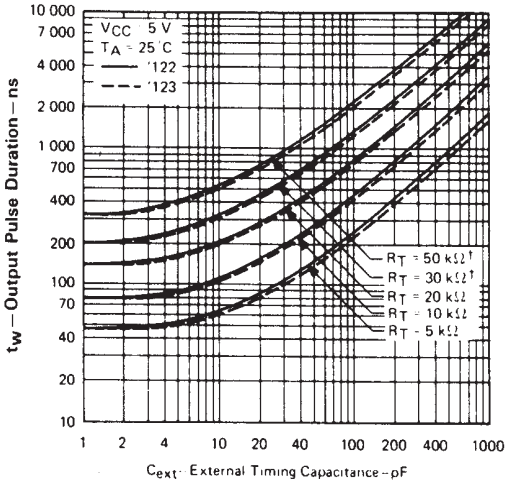


FIGURE 4

†These values of resistance exceed the maximum recommended for use over the full temperature range of the SN54' circuits.

TYPICAL APPLICATION DATA FOR 'LS122, 'LS123

The basic output pulse duration is essentially determined by the values of external capacitance and timing resistance. For pulse durations when $C_{ext} \leq 1000$ pF, use Figure 6, or use Figure 7 where the pulse duration may be defined as:

$$t_w = K \cdot R_T \cdot C_{ext}$$

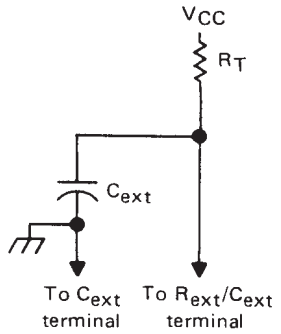
When $C_{ext} \geq 1\ \mu F$, the output pulse width is defined as:

$$t_w = 0.33 \cdot R_T \cdot C_{ext}$$

For the above two equations, as applicable;

K is multiplier factor, see Figure 7
R_T is in kΩ (internal or external timing resistance)
C_{ext} is in pF
t_w is in ns

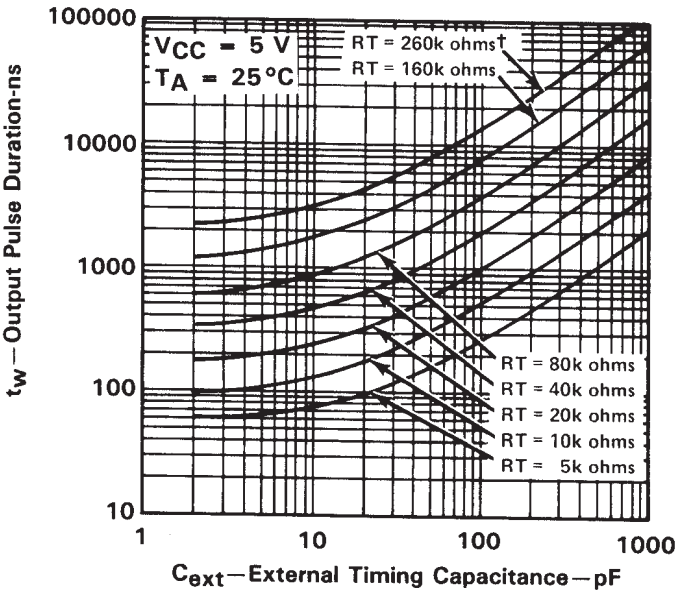
For maximum noise immunity, system ground should be applied to the C_{ext} node, even though the C_{ext} node is already tied to the ground lead internally. Due to the timing scheme used by the 'LS122 and 'LS123, a switching diode is not required to prevent reverse biasing when using electolytic capacitors.



TIMING COMPONENT CONNECTIONS

FIGURE 5

'LS122, 'LS123
TYPICAL OUTPUT PULSE DURATION
vs
EXTERNAL TIMING CAPACITANCE



†This value of resistance exceeds the maximum recommended for use over the full temperature range of the SN54LS circuits.

FIGURE 6

TYPICAL APPLICATION DATA FOR 'LS122, 'LS123†

MULTIPLIER FACTOR
vs
EXTERNAL CAPACITOR

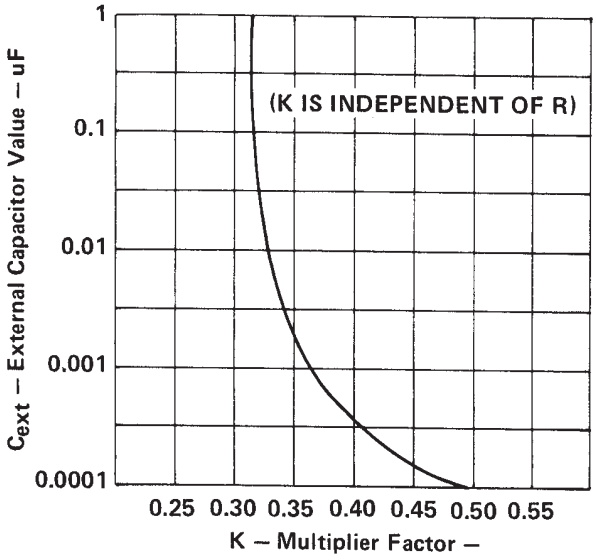


FIGURE 7

DISTRIBUTION OF UNITS
vs
OUTPUT PULSE DURATION

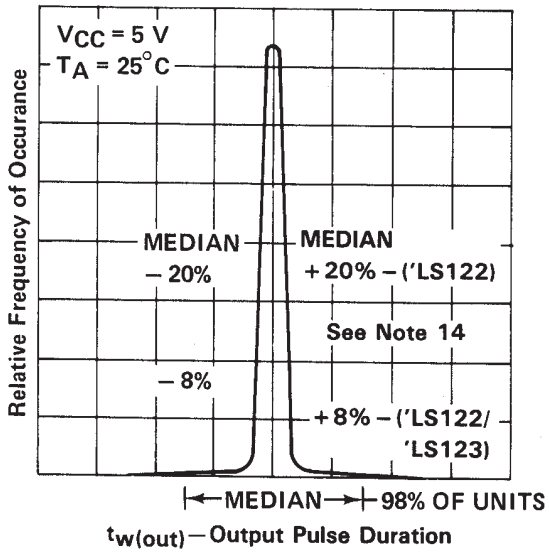


FIGURE 8

VARIATION IN OUTPUT PULSE DURATION
vs
SUPPLY VOLTAGE

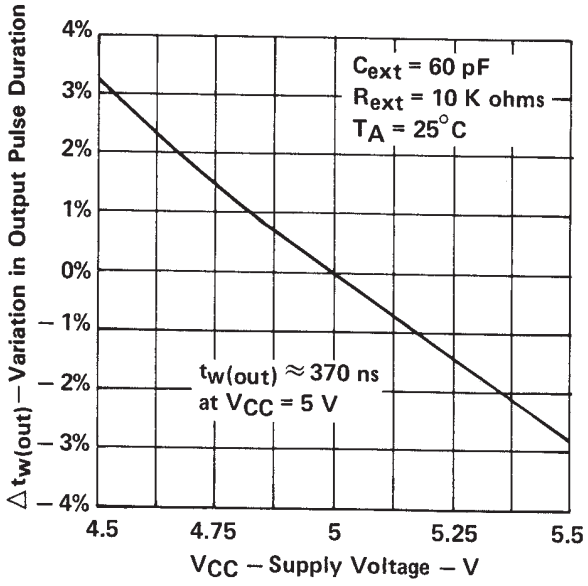


FIGURE 9

VARIATION IN OUTPUT PULSE DURATION
vs
FREE-AIR TEMPERATURE

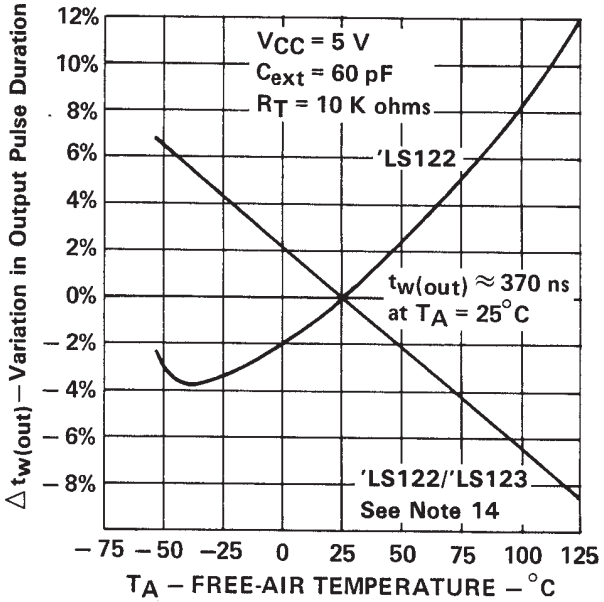


FIGURE 10

NOTE 14: For the 'LS122, the internal timing resistor, R_{int} was used. For the 'LS122/123, an external timing resistor was used for R_T.

†Data for temperatures below 0°C and above 70°C and for suply voltages below 4.75 V and above 5.25 V are applicable for SN54LS122 and SN54LS123 only.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7603901VEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7603901VEA SNV54LS123J	Samples
5962-7603901VFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7603901VFA SNV54LS123W	Samples
7603901EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901EA SNJ54LS123J	Samples
7603901FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901FA SNJ54LS123W	Samples
JM38510/01203BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 01203BEA	Samples
JM38510/31401B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401B2A	Samples
JM38510/31401BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BEA	Samples
JM38510/31401BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BFA	Samples
M38510/01203BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 01203BEA	Samples
M38510/31401B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401B2A	Samples
M38510/31401BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BEA	Samples
M38510/31401BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BFA	Samples
SN54123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54123J	Samples
SN54LS123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS123J	Samples
SN74123N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74123N	Samples
SN74LS122D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS122	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS122DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS122	Samples
SN74LS122DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS122	Samples
SN74LS122N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS122N	Samples
SN74LS122NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS122N	Samples
SN74LS122NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS122	Samples
SN74LS123D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		LS123	Samples
SN74LS123DE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS123N	Samples
SN74LS123NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS123N	Samples
SN74LS123NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS123	Samples
SN74LS123NSRG4	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS123	Samples
SNJ54123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54123J	Samples
SNJ54123W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54123W	Samples
SNJ54LS123FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 123FK	Samples
SNJ54LS123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901EA SNJ54LS123J	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS123W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901FA SNJ54LS123W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54123, SN54LS123, SN54LS123-SP, SN74123, SN74LS123 :

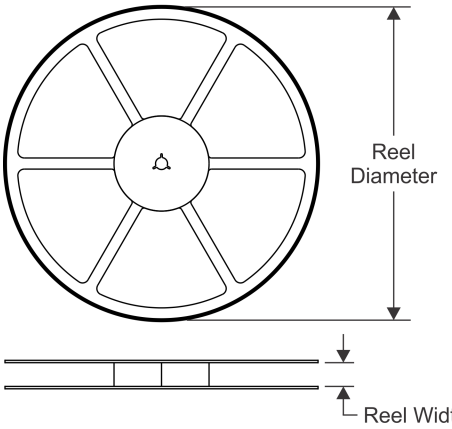
- Catalog : SN74123, SN74LS123, SN54LS123
- Military : SN54123, SN54LS123
- Space : SN54LS123-SP

NOTE: Qualified Version Definitions:

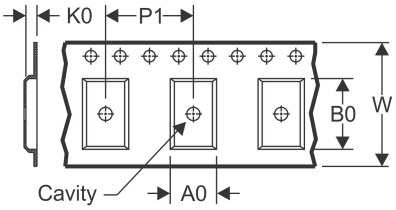
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS

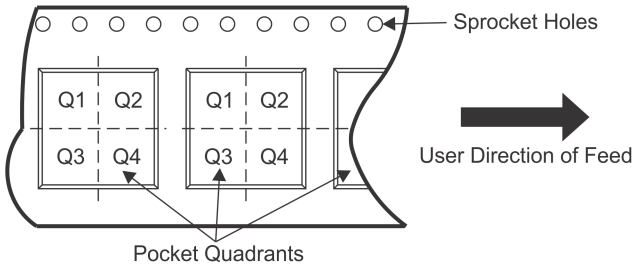


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

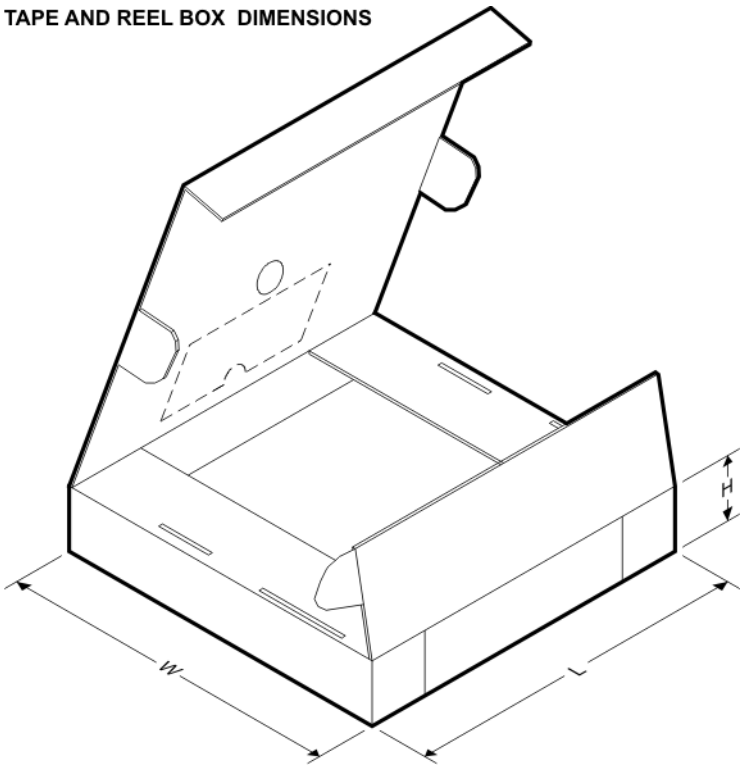
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS122DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS122NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS123DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LS123DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS123NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

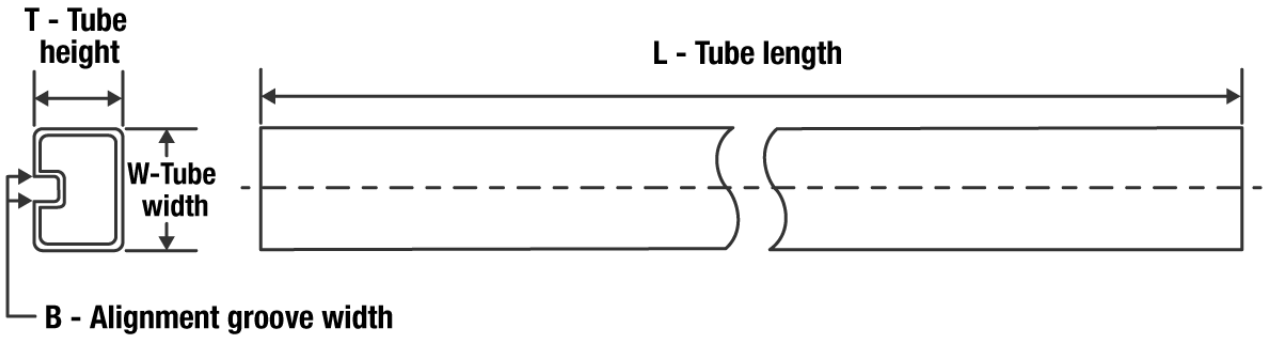
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS122DR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LS122NSR	SO	NS	14	2000	853.0	449.0	35.0
SN74LS123DBR	SSOP	DB	16	2000	853.0	449.0	35.0
SN74LS123DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS123NSR	SO	NS	16	2000	853.0	449.0	35.0

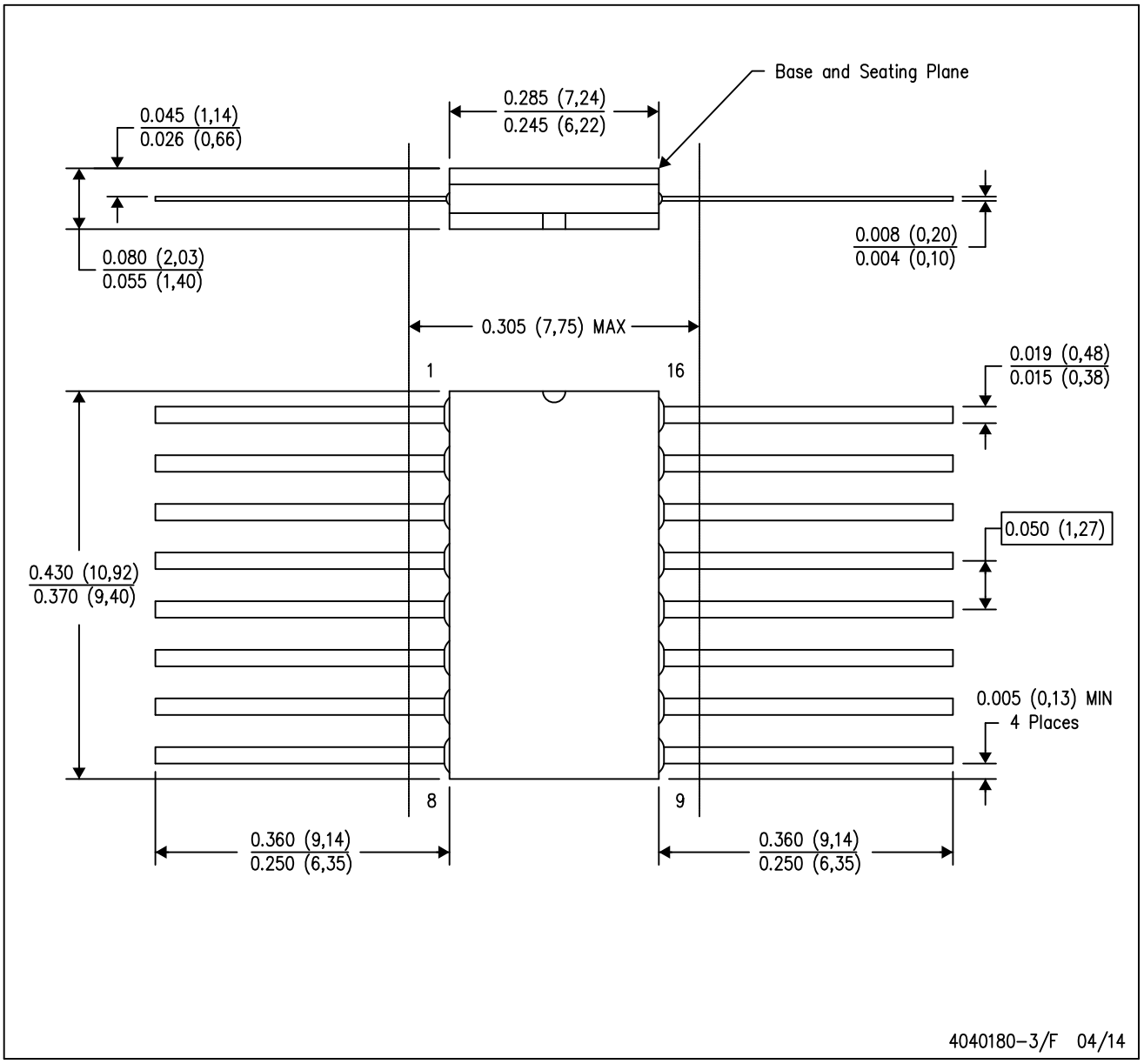
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-7603901VFA	W	CFP	16	1	506.98	26.16	6220	NA
JM38510/31401B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/31401B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS122D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS122N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS122N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS122NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS122NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS123D	D	SOIC	16	40	507	8	3940	4.32
SN74LS123DE4	D	SOIC	16	40	507	8	3940	4.32
SN74LS123DG4	D	SOIC	16	40	507	8	3940	4.32
SN74LS123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS123NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS123NE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS123FK	FK	LCCC	20	1	506.98	12.06	2030	NA

W (R–GDFP–F16) CERAMIC DUAL FLATPACK

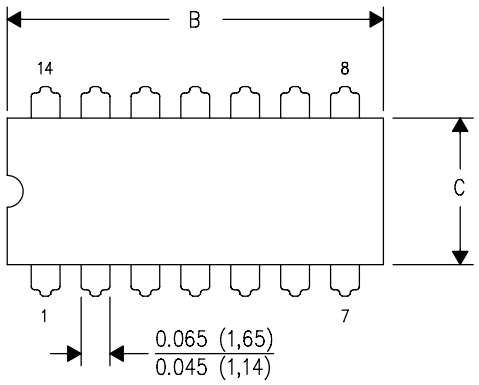


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

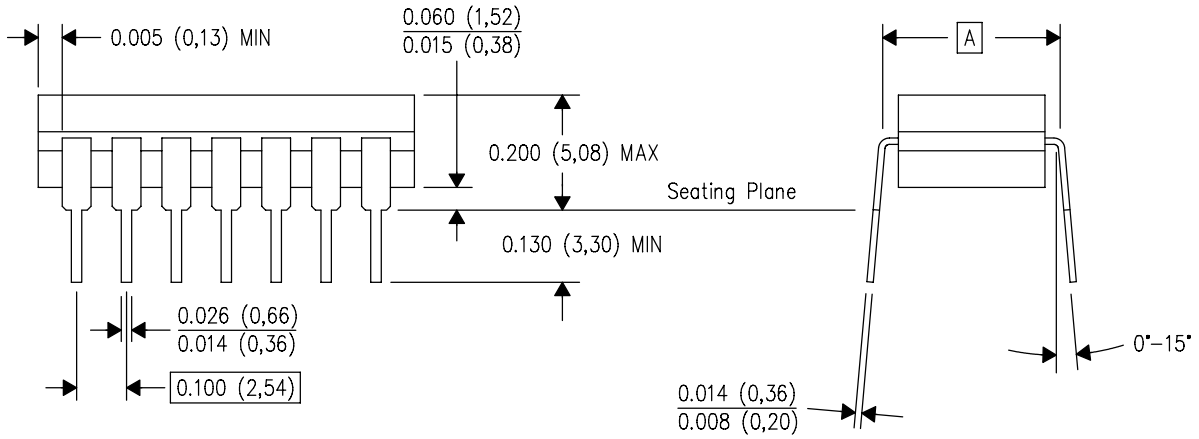
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



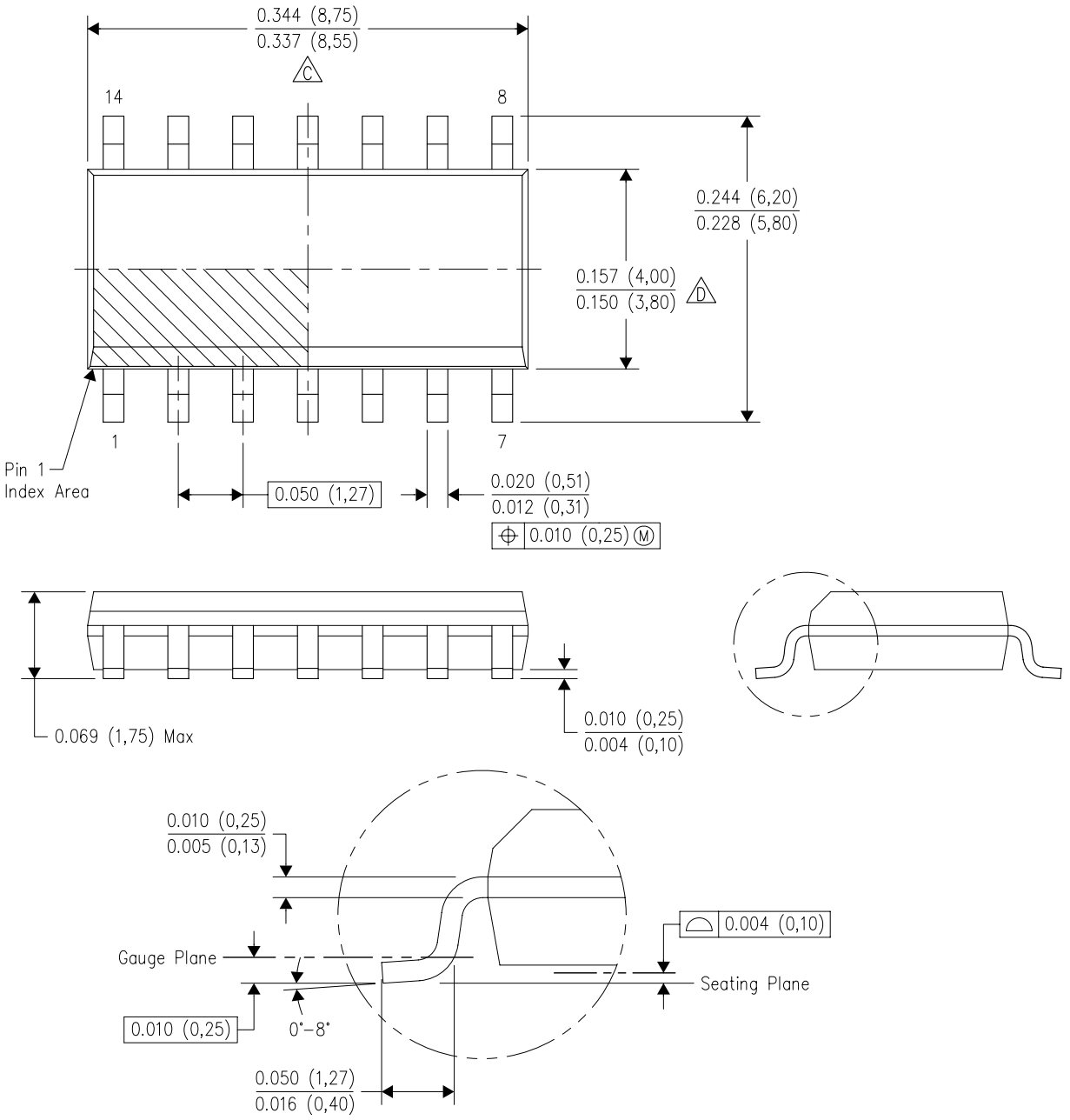
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

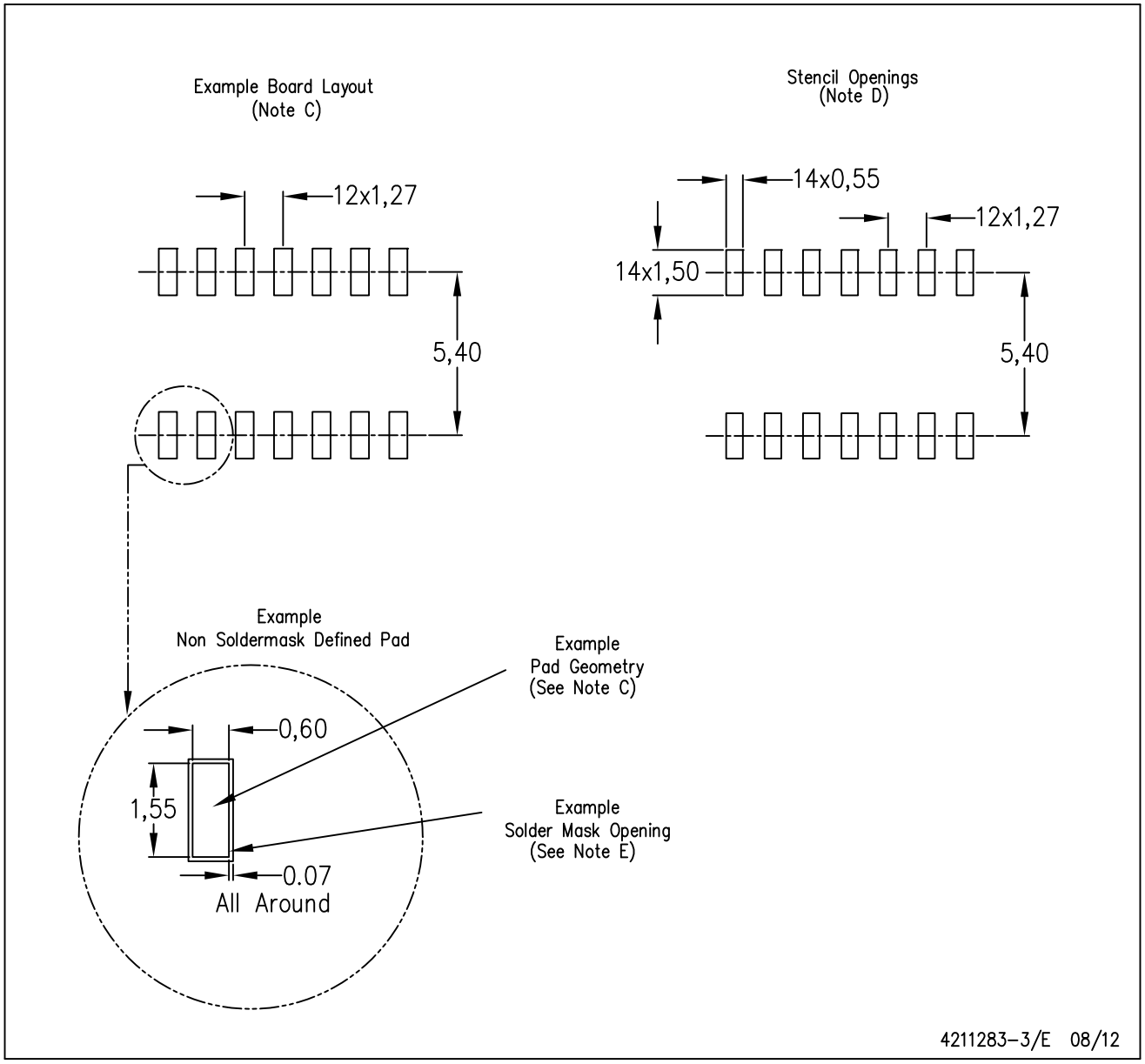
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE

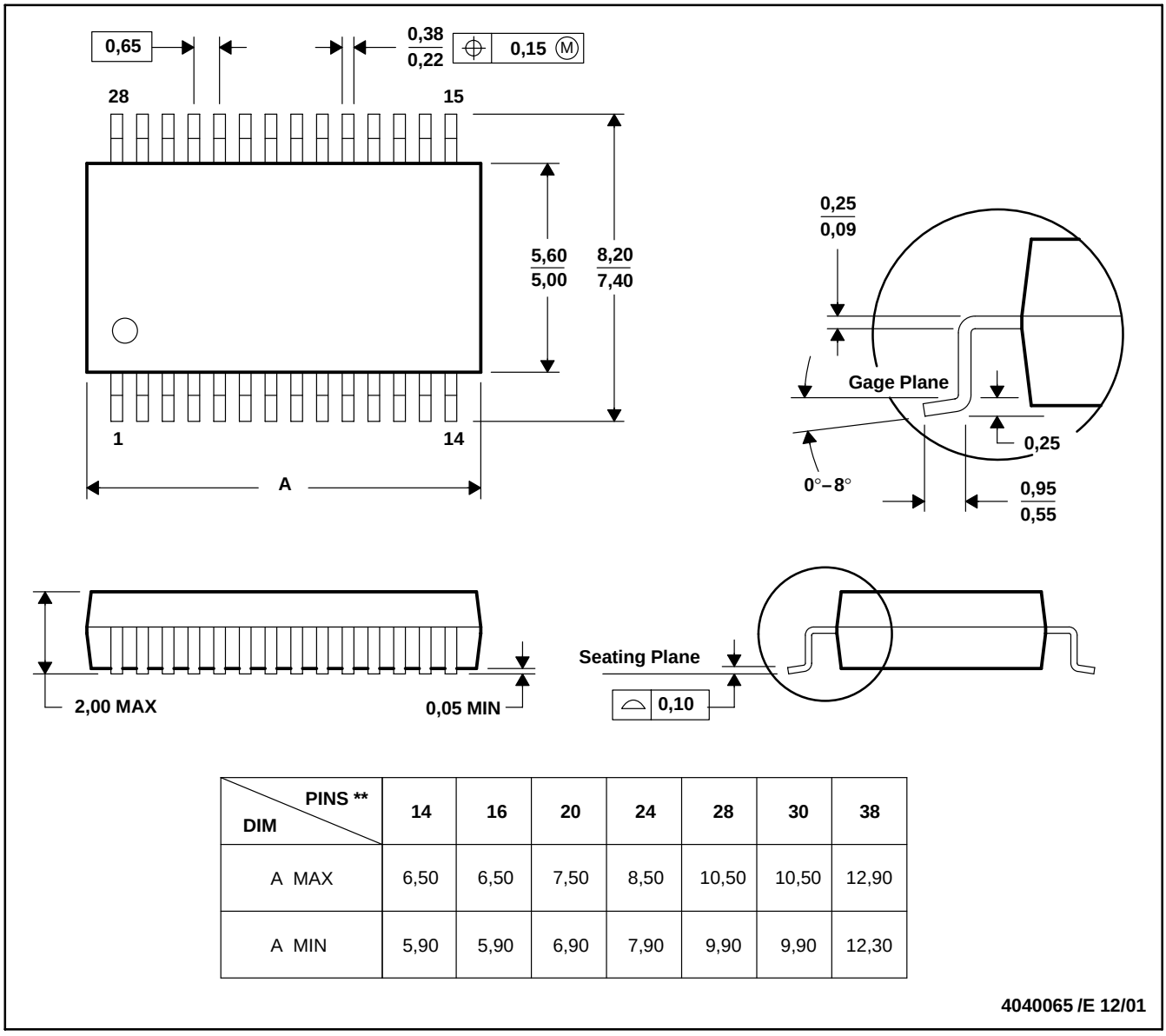


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

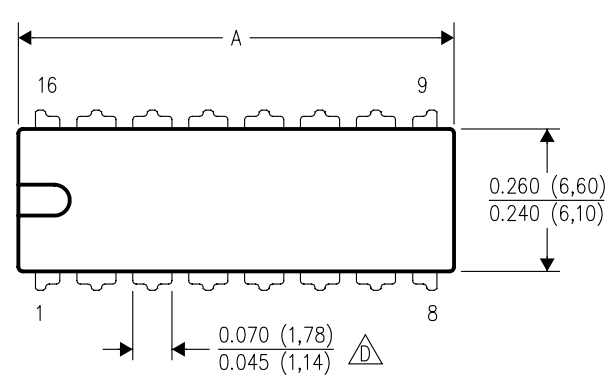
4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

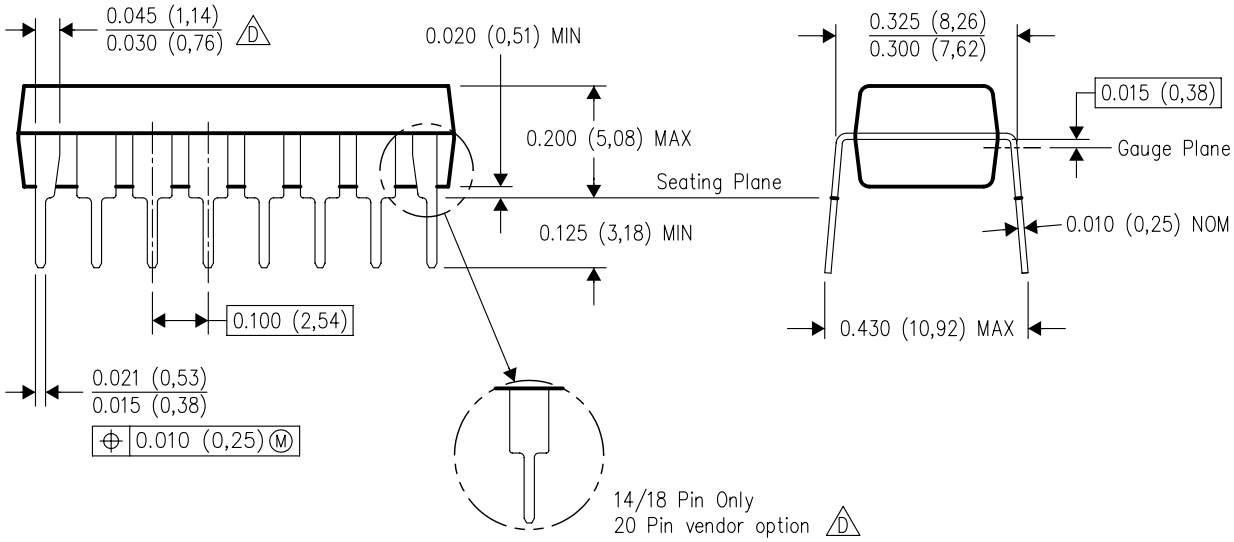
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

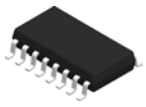


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

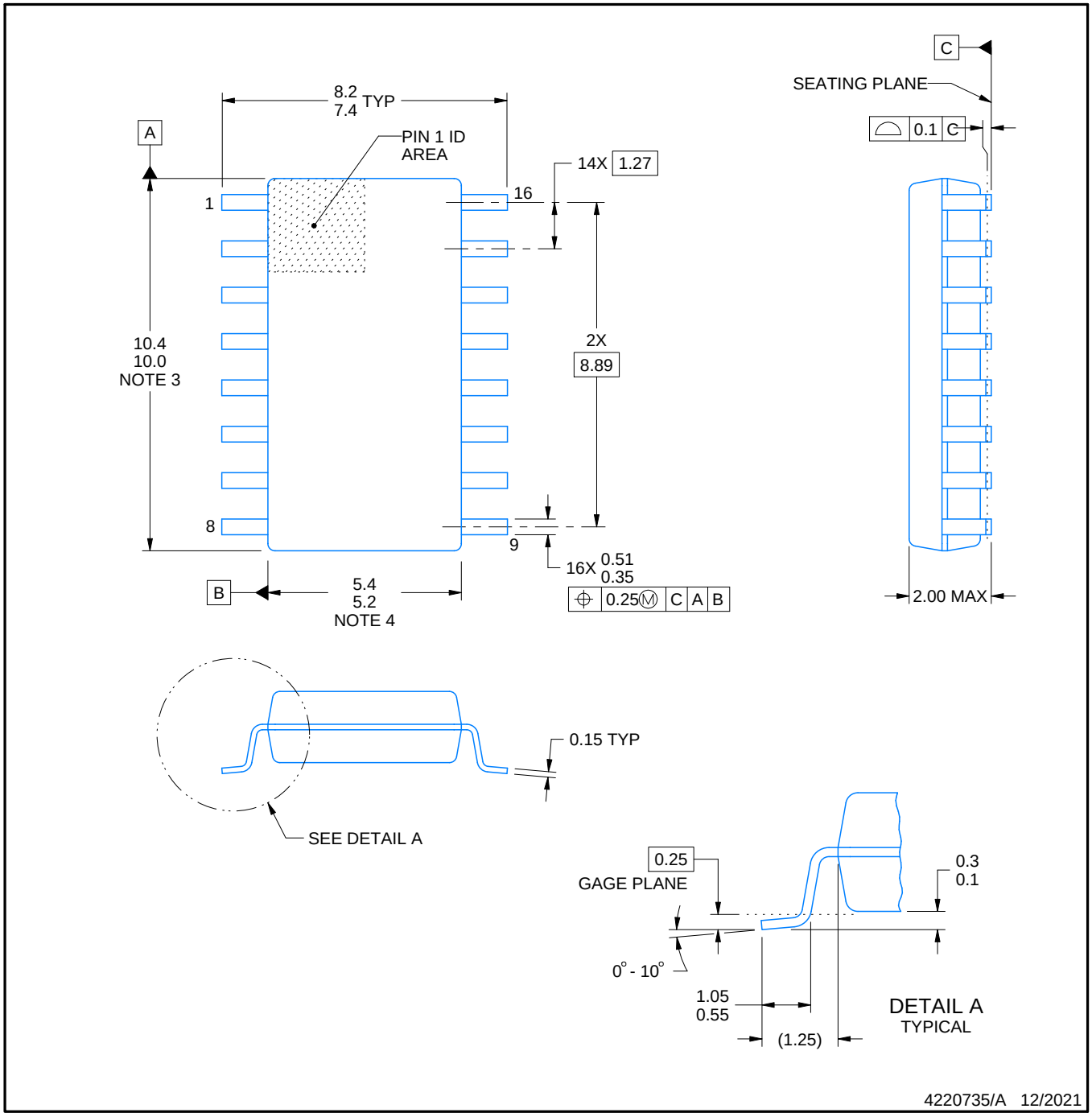


PACKAGE OUTLINE

NS0016A

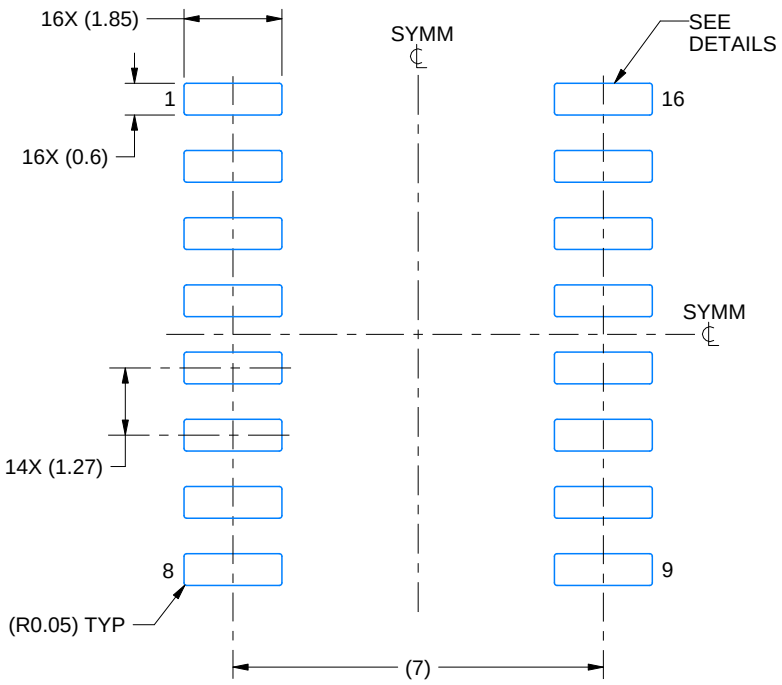
SOP - 2.00 mm max height

SOP

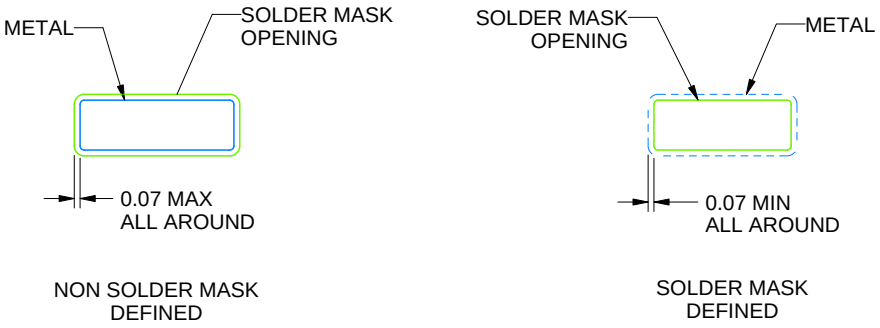


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

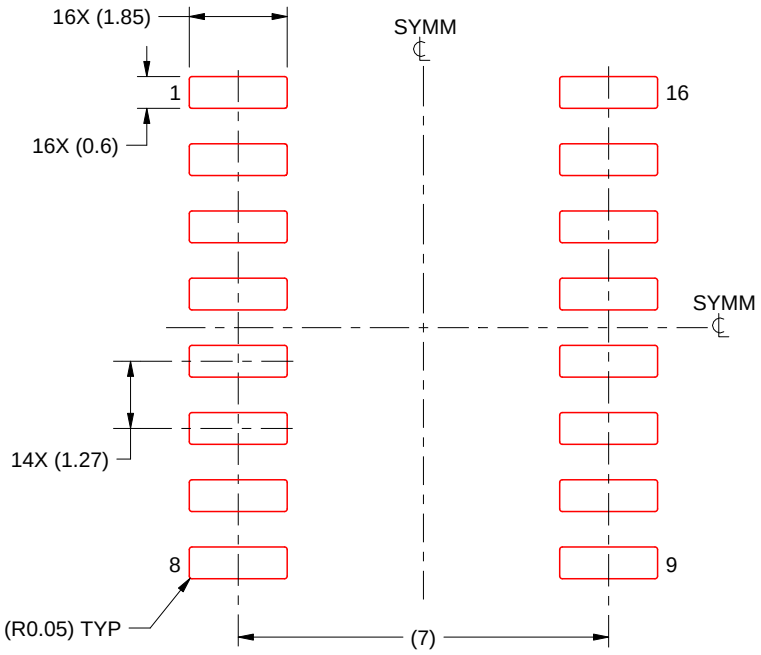
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

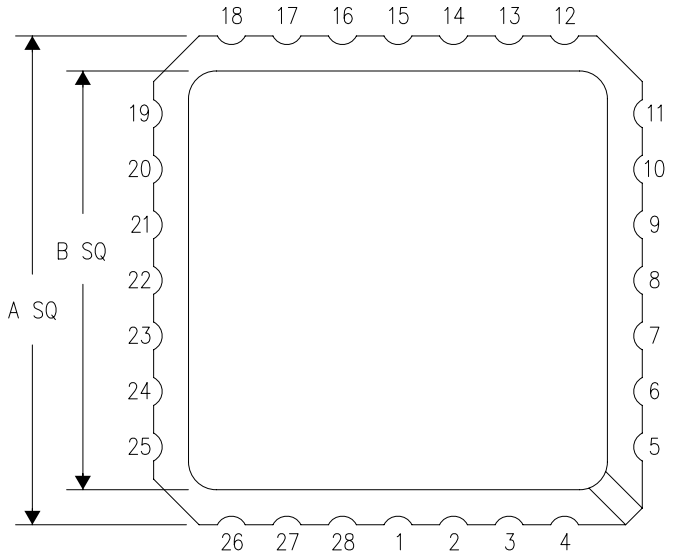
4220735/A 12/2021

NOTES: (continued)

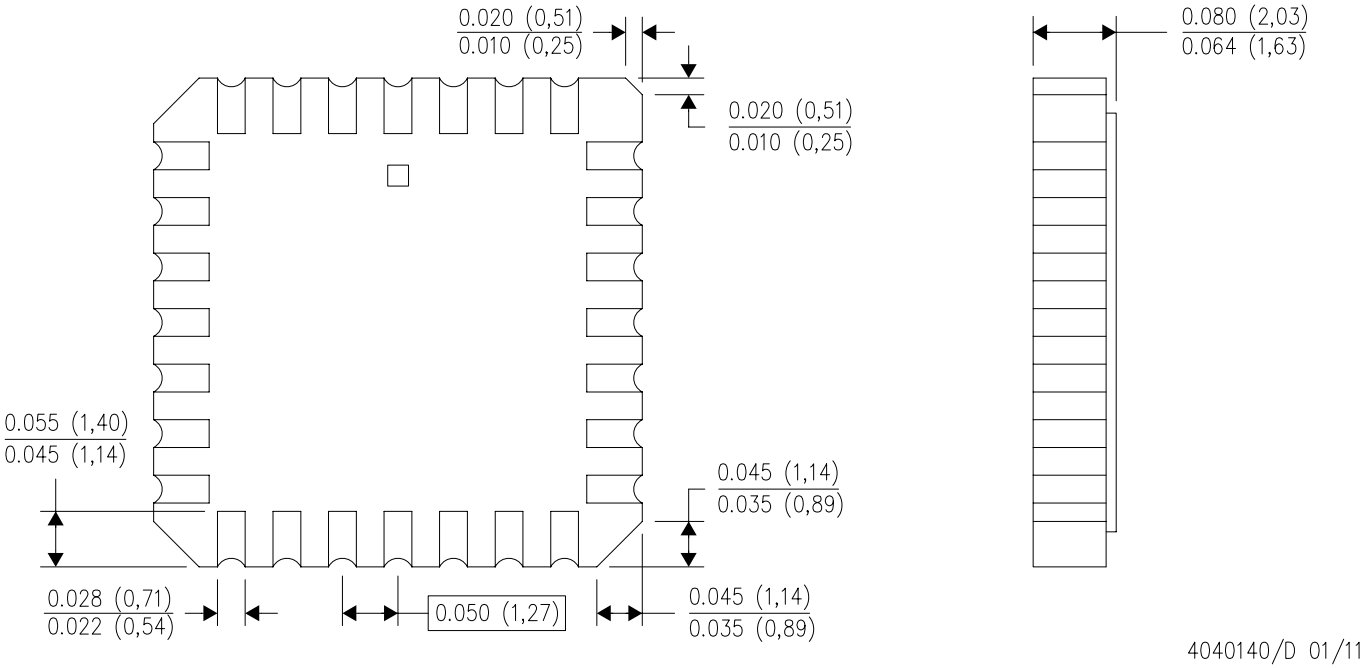
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



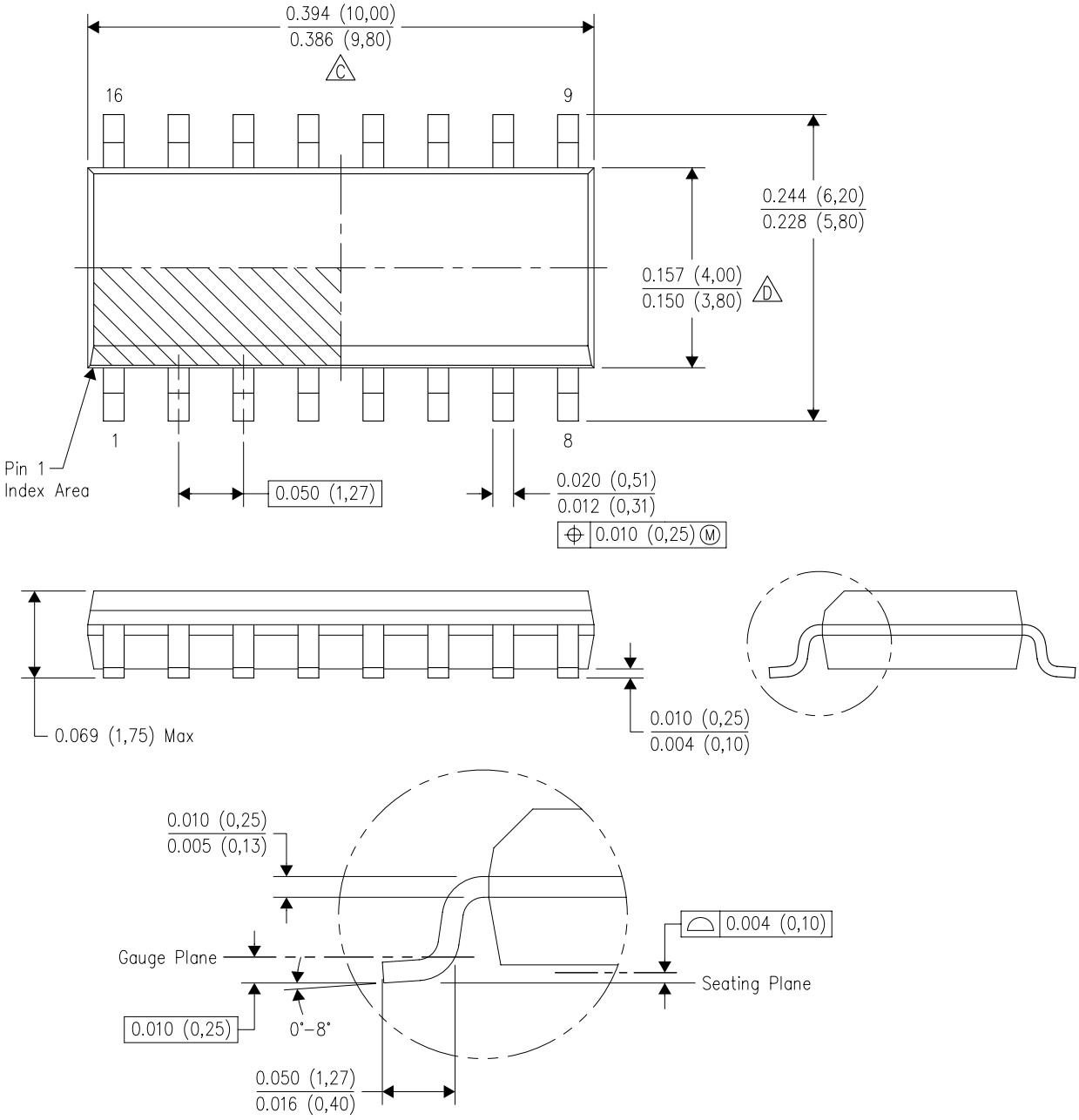
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

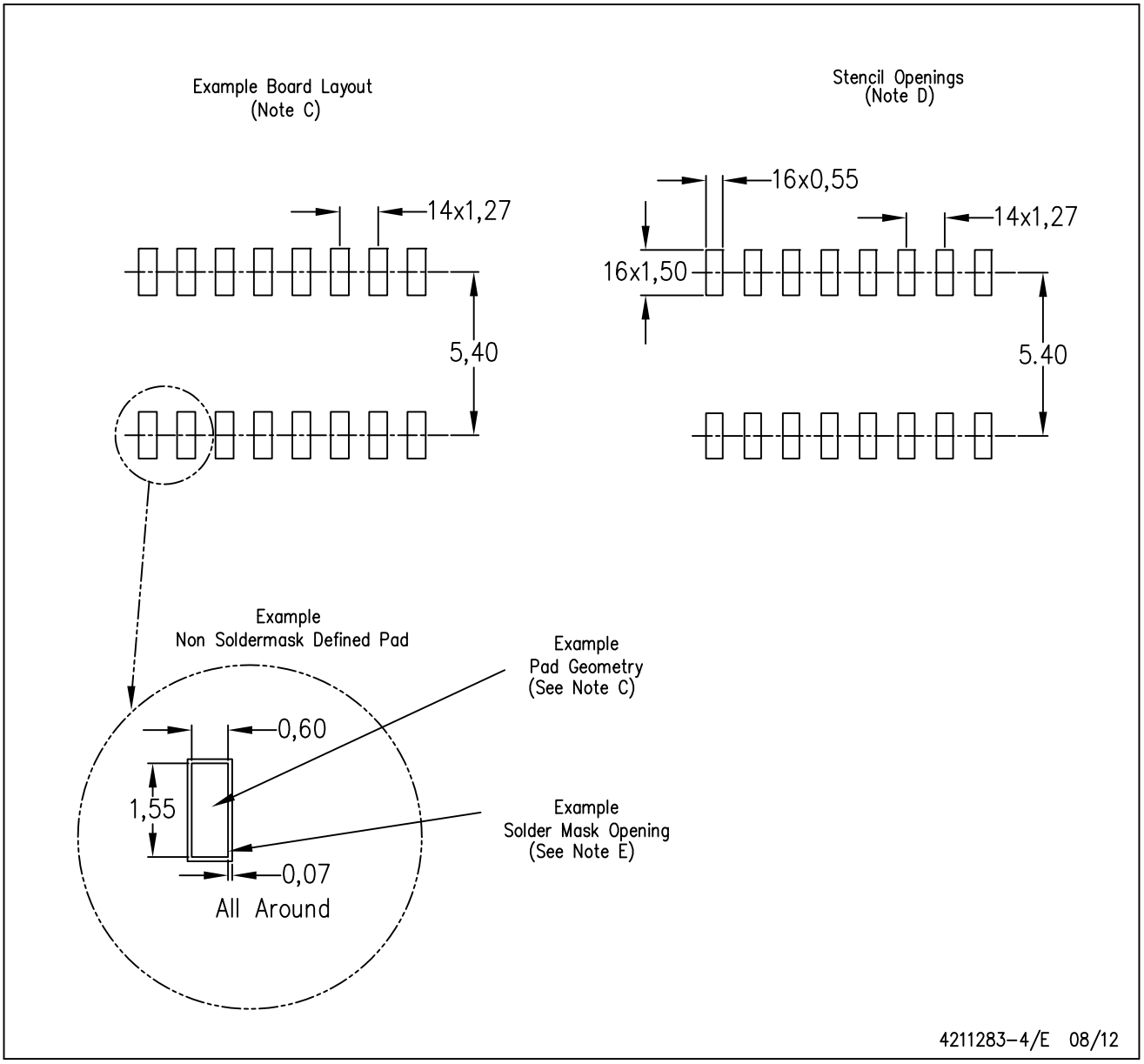
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

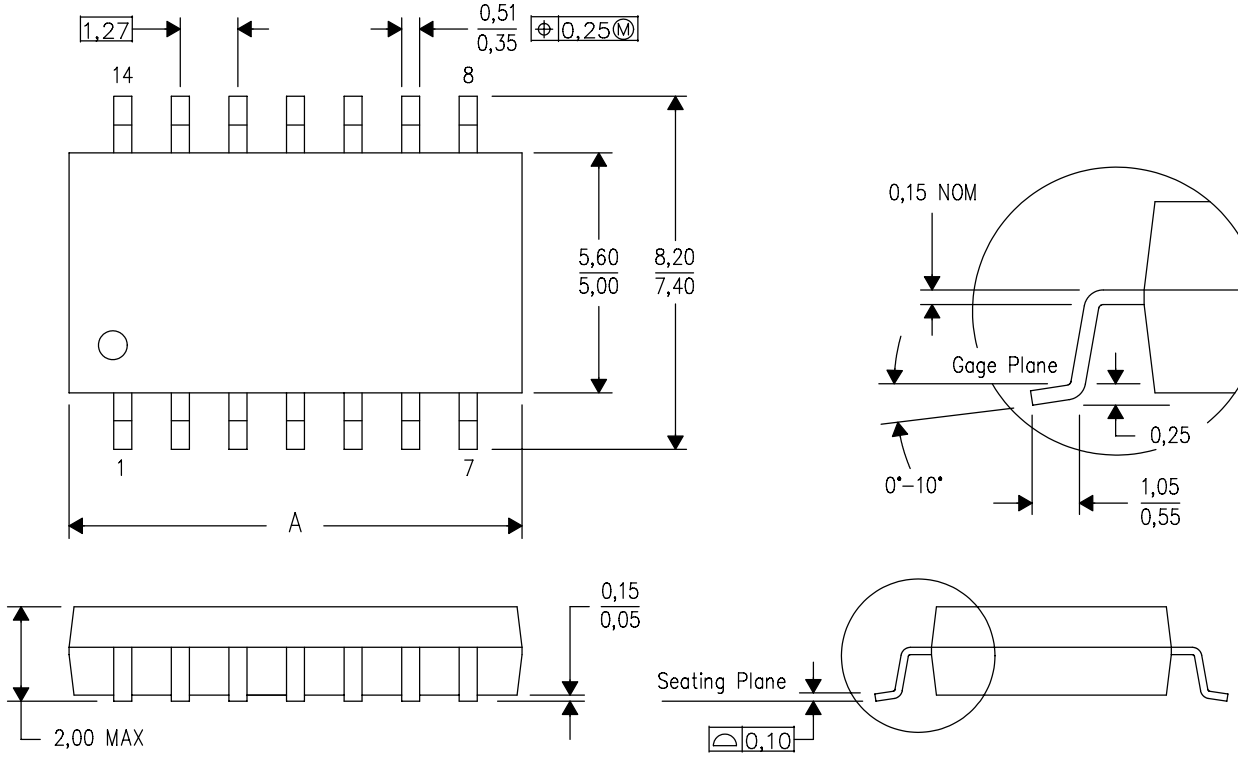


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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